

AMENDMENTS TO THE CLAIMS:

This listing of claims replaces all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (Currently Amended) A printed circuit board assembly including:
a first circuit board having a first device side, the first device side having a first portion configured to mount a first ~~plurality of semiconductor device devices~~;
a second circuit board having a second device side, the second device side having a second portion configured to mount a second ~~plurality of semiconductor device devices~~, the second circuit board disposed in confronting parallel relationship to the first circuit board; and
a border interposed between the first and second boards and disposed around the respective first and second portions, the border ~~element-cooperating forming~~ with the first and second boards to form a liquid-tight chamber containing the first and second semiconductor devices container, the border ~~formed with~~ includes an inlet to receive an electrically nonconducting liquid into the chamber and an outlet for discharging the liquid from the chamber.

2. (Currently Amended) A ~~The printed circuit board~~ assembly ~~according to~~ of claim 1 wherein the first and second circuit boards comprise channel cards for use in a semiconductor tester.

3. (Currently Amended) A ~~The printed circuit board~~ assembly ~~according to~~ of claim 1 wherein the border comprises:

a border element having a thin metallic wall of a uniform height and respective top and bottom sealing edges; and

respective first and second seals disposed between the top and bottom sealing edges and the first and second device sides.

4. (Currently Amended) A ~~The printed circuit board~~ assembly ~~according to~~ of claim 1 wherein the first and second printed circuit boards have devices mounted solely on the first and second device sides.

5. (Currently Amended) Automatic test equipment comprising ~~including~~:
~~a computer workstation; and~~
a testhead adapted for being carried by a manipulator, the testhead including a plurality of printed circuit board assemblies, each of the plurality of circuit board assemblies including:
a first circuit board having a first device side, the first device side having a first portion configured to mount a first ~~plurality of semiconductor~~ device ~~devices~~;

a second circuit board having a second device side, the second device side having a second portion configured to mount a second ~~plurality of semiconductor~~ device devices, the second circuit board disposed in confronting parallel relationship to the first circuit board; and

a border interposed between the first and second boards and disposed around the respective first and second portions, the border ~~cooperating~~ forming with the first and second boards ~~to form~~ a liquid-tight chamber containing the first and second semiconductor devices container, the border ~~formed with~~ including an inlet to receive an electrically nonconducting liquid into the chamber and an outlet for discharging the liquid from the chamber.

6. (Currently Amended) The automatic ~~Automatic~~ test equipment of ~~according to~~ claim 5 wherein the border comprises:

a border element having a thin metallic wall of a uniform height and respective top and bottom sealing edges; and

respective first and second seals disposed between the top and bottom sealing edges and the first and second device sides.

7. (Currently Amended) The automatic ~~Automatic~~ test equipment of ~~according to~~ claim 5 wherein the first and second printed circuit boards have devices mounted solely on the first and second device sides.

8. (Original) A method of ~~cooling a plurality of electronic devices, the method comprising including the steps:~~

cooling electronic devices, cooling comprises:

mounting the electronic devices on confronting sides of a pair of printed circuit boards, the circuit boards placed in a parallel stacked relationship; and

interposing a border between the circuit boards and around the electronic devices, the border ~~cooperating~~ with the boards forming to establish a liquid-tight chamber containing the electronic devices, the border including an inlet to receive an electrically nonconducting liquid into the chamber and an outlet for discharging the liquid from the chamber liquidtight container;

~~immersing the electronic devices into an electrically nonconducting liquid inside the container.~~

9. (New) The method of claim 8, further comprising discharging the electrically nonconducting liquid into the chamber.

10. (New) The method of claim 9, further comprising immersing the electronic devices with the electrically nonconducting liquid with the chamber.

11. (New) The method of claim 9, further comprising discharging the electrically nonconducting liquid from the chamber.